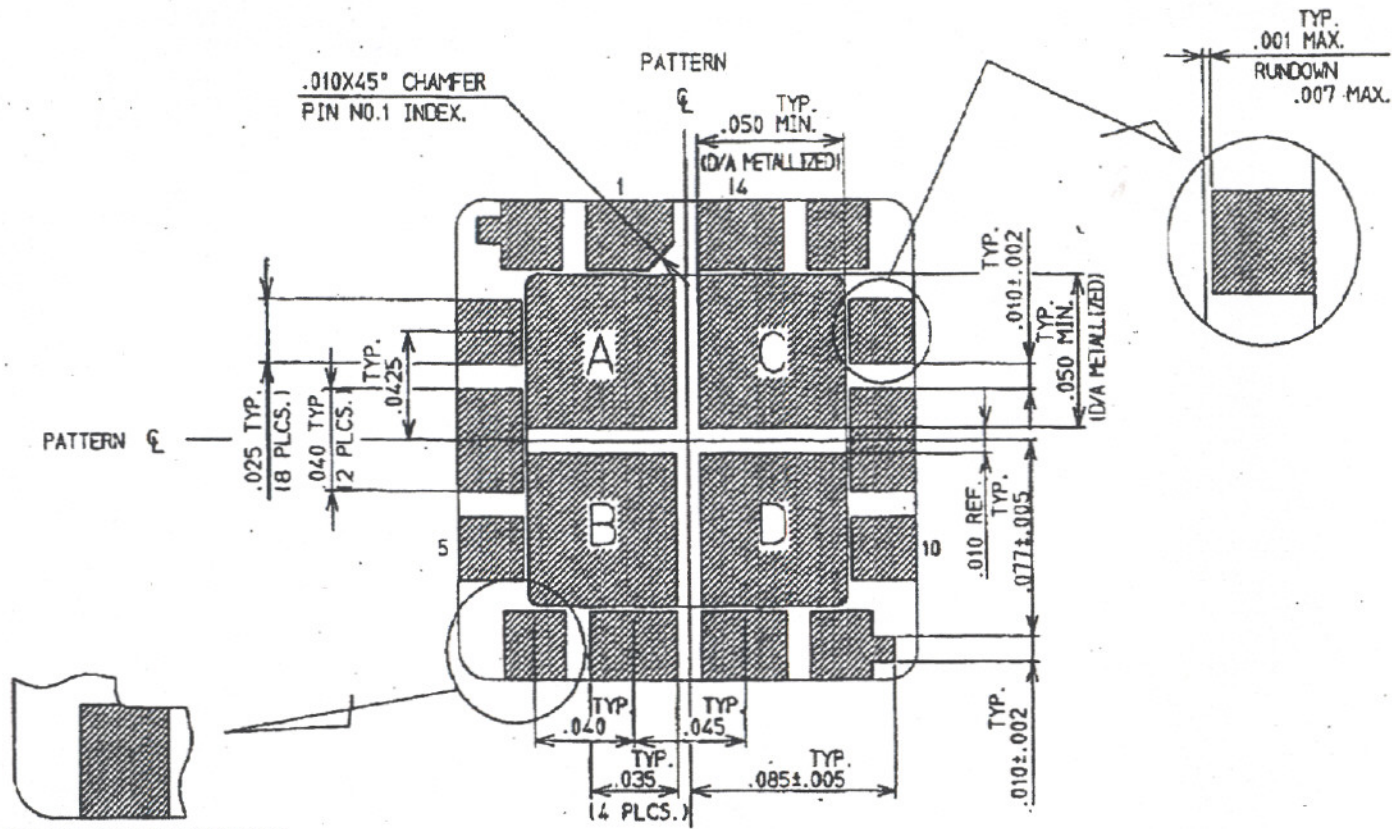


- NOTES:
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING TO BE FLOATING FROM ANY PINS.
 5. DIE ATTACH AREA CONNECTION: A-L/F#LB-#7.D-#8.C-#14
 6. LEAD RESISTANCE: 0.150 MAX.

MODIFICATION					REV	14 LEAD FLAT PACKAGE	14 LEAD FLAT PACKAGE	DRWN	DESIGN	PRPDR	DATE	FW014AF847-1 S=0 D=1.7.8.14
					SCALE	B / 1	MATERIAL AS INDICATED	S.T.H	K.M.S.F.	T.A	JUL 21 '81	
							.005					
	OWNED				DATE	DRWN	DESIGN	PRPDR	KYOCERA		KYOCERA CORPORATION KYOTO JAPAN	Model No. KD-F97847



BONDING PATTERN

MODIFICATIONS					
	CHANGE	DATE	DRAWN	CHECKED	APPROVED

NAME	14 LEAD FLAT PACKAGE
SCALE	20 / 1
MATERIAL	

TOLERANCES:
UNLESS OTHERWISE SPECIFIED
—
SHOULDER PROJECTION

DRAWN	CHECKED	APPROVED	DATE
S. TH	K.M/S.F	T.A	JUL 25 '91
DRAWING NO.			SHEET
KD-F97847			2 / 2



KYOCERA CORPORATION
KYOTO JAPAN